

Title (en)

HIGH DENSITY FILAMENT WINDING AND METHOD FOR PRODUCING IMPROVED CROSSOVERS AND INSIDE PAYOUT.

Title (de)

HOCHDICHTES GARNAUFSPULEN UND VERFAHREN ZUR HERSTELLUNG VERBESSERTER KREUZUNGSSTELLEN UND ZUM BESSEREN ABSPULEN.

Title (fr)

ENROULEMENT DE FILAMENT DE HAUTE DENSITE ET PROCEDE DE PRODUCTION DE CROISEMENTS ET DE DEROULEMENT INTERIEUR AMELIORES.

Publication

EP 0396735 B1 19931020 (EN)

Application

EP 90901102 A 19890911

Priority

US 26380488 A 19881028

Abstract (en)

[origin: WO9004562A2] Method and apparatus for making a filament winding amenable to inside payout and having squared-off ends providing optimal volumetric efficiency. The filament crossovers are distributed so as to reduce crossover stacking in one or a few places which can interfere with winding and payout from the finished winding. A base wire layer (48) is wrapped onto a mandrel (30) over which a guide (52) is nestingly wound with adjacent guide wire turns spaced apart. The filament first layer is wound nesting in the guide wire, spaces (54), and subsequent filament layers (56) accordingly formed. Each crossing filament turn has an advance in a crossing region substantially aligned with a crossover region in the underlying layer and which in one embodiment is one-half the winding pitch.

IPC 1-7

B65H 55/04; **F42B 15/04**

IPC 8 full level

H01B 1/12 (2006.01); **B65H 55/04** (2006.01); **C07F 7/08** (2006.01); **C08G 77/48** (2006.01); **C08G 77/60** (2006.01); **F41G 7/32** (2006.01); **F42B 15/04** (2006.01); **G02B 6/04** (2006.01); **G02B 6/44** (2006.01)

CPC (source: EP)

B65H 55/04 (2013.01); **C07F 7/0803** (2013.01); **G02B 6/04** (2013.01); **G02B 6/4457** (2013.01); **B65H 2515/12** (2013.01)

Designated contracting state (EPC)

CH DE FR GB IT LI NL SE

DOCDB simple family (publication)

WO 9004562 A2 19900503; **WO 9004562 A3 19900531**; AU 4661289 A 19900514; AU 617564 B2 19911128; AU 622839 B2 19920416; AU 8342891 A 19911031; CA 1329715 C 19940524; DE 68910112 D1 19931125; DE 68910112 T2 19940210; EP 0396735 A1 19901114; EP 0396735 B1 19931020; ES 2018934 A6 19910516; IL 91658 A 19960912; JP H03501266 A 19910322; JP H03503155 A 19910718; JP H0671989 B2 19940914

DOCDB simple family (application)

US 8903875 W 19890911; AU 4661289 A 19890911; AU 8342891 A 19910827; CA 612092 A 19890920; DE 68910112 T 19890911; EP 90901102 A 19890911; ES 8903635 A 19891027; IL 9165889 A 19890915; JP 50117289 A 19890117; JP 50117290 A 19890911